AMENDMENT

Listing of Claims

Please amend the claims as follows:

1. (Currently Amended) A system for channeling high frequency signals within an electronic device, comprising:

a midplane circuit board;

a midplane chassis shield disposed adjacent to said midplane circuit board;

an interface module suitable for being coupled to said midplane circuit board through said midplane chassis shield, the interface module including an EMC seal;

wherein said midplane circuit board, midplane chassis shield and interface module cooperate for providing a low impedance tunnel for channeling high frequency signals to ground.

2. (Original) The system according to claim 1, wherein said interface module comprises an interface module container and an interface circuit board, said interface circuit board being substantially contained within said interface module container.

3. (Original) The system according to claim 2, further comprising an interface connector suitable for coupling said interface circuit board to said midplane circuit board said interface connector including a first connector half coupled to said interface circuit board and a second connector half coupled to said midplane circuit board.

4. (Original) The system according to claim 3, wherein said first connector half comprises an interface connector shield further cooperating with said midplane circuit board, midplane chassis shield and interface module cooperate for providing a low impedance tunnel for channeling high frequency signals to ground.

5. (Original) The system according to claim 4, further comprising a gasket disposed between said interface connector shield and said interface module container.

6. (Original) The system according to claim 3, wherein said connector further comprises at least one logic pin and at least one ground shield pin.

7. (Original) The system according to claim 2, wherein said interface module container further comprises at least one suspension ground spring suitable for substantially holding said interface module in said electronic device.

8. (Original) The system according to claim 1, wherein said midplane chassis shield comprises at least one guide for securing said interface module to said midplane chassis.

9. (Cancelled)

10. (Currently Amended) An electronic device, comprising:

a housing;

a midplane circuit board;

a midplane chassis shield disposed in said housing adjacent to said midplane circuit board;

an interface module suitable for being coupled to said midplane circuit board through said midplane chassis shield, the interface module including an EMC shield;

wherein said midplane circuit board, midplane chassis shield and interface module cooperate for providing a low impedance tunnel for channeling high frequency signals to ground.

11. (Original) The electronic device according to claim 10, wherein said interface module comprises an interface module container and an interface circuit board, said interface circuit board being substantially contained within said interface module container.

12. (Original) The electronic device according to claim 11, further comprising an interface connector suitable for coupling said interface circuit board to said midplane circuit board said interface connector including a first connector half coupled to said interface circuit board and a second connector half coupled to said midplane circuit board.

13. (Original) The electronic device according to claim 12, wherein said first connector half comprises an interface connector shield further cooperating with said midplane circuit board, midplane chassis shield and interface module cooperate for providing a low impedance tunnel for channeling high frequency signals to ground.

14. (Original) The electronic device according to claim 13, further comprising a gasket disposed between said interface connector shield and said interface module container.

15. (Original) The electronic device according to claim 14, wherein said connector further comprises at least one logic pin and at least one ground shield pin.

16. (Original) The electronic device according to claim 11, wherein said interface module container further comprises at least one suspension ground spring suitable for substantially holding said interface module in said electronic device.

17. (Original) The electronic device according to claim 10, wherein said midplane chassis shield comprises at least one guide for securing said interface module to said midplane chassis.

18. (Cancelled)

19. (Original) A system for channeling high frequency data signals within an electronic device, comprising:

a housing;

a midplane circuit board disposed in said housing;

an interface module suitable for being coupled to said midplane circuit board;

means for providing a low impedance tunnel for channeling high frequency signals in said midplane circuit board and interface module to ground.

20. (Original) The system as claimed in claim 19, further comprising means for removably mounting said interface module in said housing wherein said interface module is coupled to said midplane circuit board.